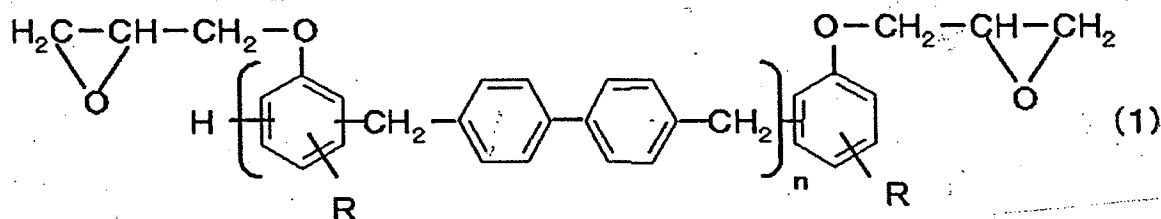


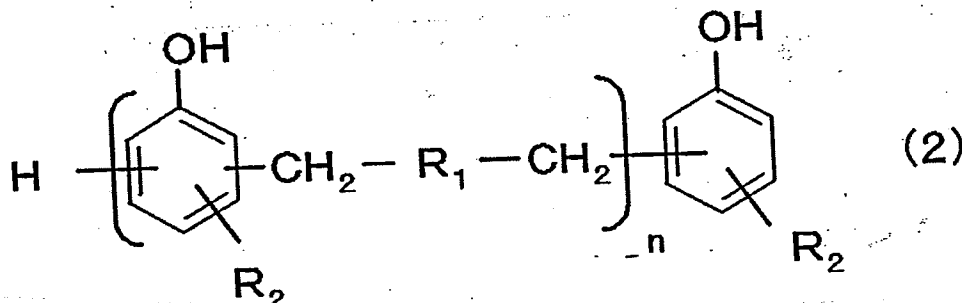
Amendments to the Specification

On page 3, replace lines 3-16 with the following:

This invention provides a resin composition for encapsulating a semiconductor chip comprising: an epoxy resin (A) represented by general formula (1):



wherein R represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average; a phenol resin (B) represented by general formula (2):

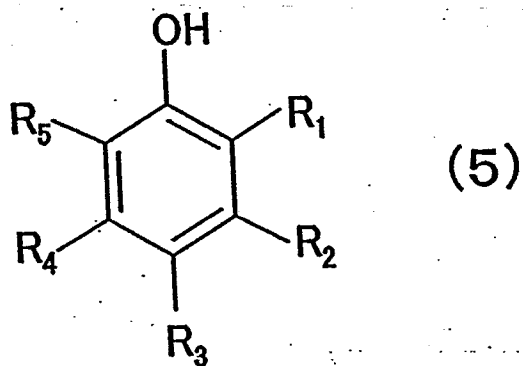


wherein R₁ represents phenylene or biphenylene; R₂ represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average; an inorganic filler (C); a curing accelerator (D); a silane coupling agent (E); and Compound (F) containing two and more hydroxyl groups ~~combined with each of~~ on adjacent carbon atoms comprising an aromatic ring.

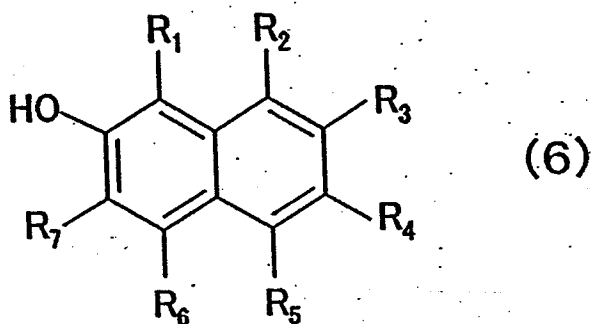
On page 13, please replace the paragraph beginning on line 4 to page 14, line 2, with the following:

Compound (F) containing two and more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring may contain optionally a substituent other than the hydroxyl groups.

Compound (F) may be a monocyclic compound represented by general formula (5):



wherein one of R₁ and R₅ is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than hydroxyl; and R₂, R₃ and R₄ are hydrogen, hydroxyl or a substituent other than hydroxyl; or a polycyclic compound represented by general formula (6):



wherein one of R_1 and R_7 is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than ~~hydroxyl~~hydroxyl; and R_2 , R_3 , R_4 , R_5 and R_6 are hydrogen, hydroxyl or a substituent other than hydroxyl.

Please replace Table 1 on page 21 with the following table:

TABLE 1

	Examples										
	1	2	3	4	5	6	7	8	9	10	11
Phenol bisphenylalkyl type epoxy resin	7.35	4.0	8.05	7.5	7.13	7.42	7.35	7.35	7.35	7.35	7.35
Bisphenyl type epoxy resin	5.5	1.0									
Phenol bisphenylalkyl resin	5.5	2.5	5.5	5.5	5.3	5.5	5.5	5.5	5.5	5.45	5.45
Phenolalkyl resin		1.3									
Spherical fused silica	86.0	90.0	84.5	88.0	88.0	88.0	88.0	88.0	88.0	88.0	86.0
γ -Glycidypropyltrimethoxysilane	0.4	0.5	0.3	0.05	0.85	0.03	0.4		0.4	0.4	0.4
7-Mercaptoheptyltrimethoxysilane								0.2			
Trichlorophosphine	0.2	0.13	0.25	0.2	0.2	0.2	0.2	0.2	0.2		
DBU									0.2		
Curing accelerator of formula (7)										0.25	
Curing accelerator of formula (8)											0.25
2,3-Dihydroxynaphthalene	0.05	0.07	0.1	0.25	0.02	0.35		0.05	0.05	0.05	0.05
1,2-Dihydroxynaphthalene							0.05				
Glycidol											
Pyrogallol											
1,5-Dihydroxynaphthalene											
Resorcinol											
Oxmaul wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spinel flaw	100	85	121	115	86	118	104	109	102	112	105
During torque ratio (%)	85	81	88	60	68	58	63	63	61	85	89
Chips delamination	0	0	0	0	0	0	0	0	0	0	0
Solder resistance-cracking	0	0	0	0	0	0	0	0	0	0	0
Internal crack	0	0	0	0	0	0	0	0	0	0	0
Fire retardancy	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0